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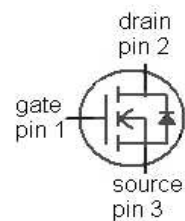
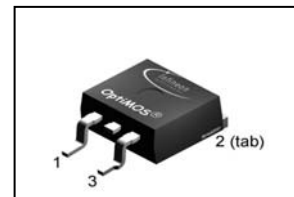


OptiMOS[®] Power-Transistor
Features

- N-channel Logic Level - Enhancement mode
- Automotive AEC Q101 qualified
- MSL1 up to 260°C peak reflow
- 175°C operating temperature
- **Green package (lead free)**
- Ultra low Rds(on)
- 100% Avalanche tested

Product Summary

| | | |
|--------------------------------|----|----|
| V_{DS} | 55 | V |
| $R_{DS(on),max}$ (SMD version) | 35 | mΩ |
| I_D | 30 | A |

PG-TO252-3-11


| Type | Package | Marking |
|----------------|---------------|---------|
| IPD26N06S2L-35 | PG-TO252-3-11 | 2N06L35 |

Maximum ratings, at $T_j=25\text{ °C}$, unless otherwise specified

| Parameter | Symbol | Conditions | Value | Unit |
|-------------------------------------|-------------------|--|--------------|------|
| Continuous drain current | I_D | $T_C=25\text{ °C}$, $V_{GS}=10\text{ V}$ | 30 | A |
| | | $T_C=100\text{ °C}$, $V_{GS}=10\text{ V}^{1)}$ | 22 | |
| Pulsed drain current ¹⁾ | $I_{D,pulse}$ | $T_C=25\text{ °C}$ | 120 | |
| Avalanche energy, single pulse | E_{AS} | $I_D=26\text{ A}$ | 80 | mJ |
| Gate source voltage | V_{GS} | | ±20 | V |
| Power dissipation | P_{tot} | $T_C=25\text{ °C}$ | 68 | W |
| Operating and storage temperature | T_j , T_{stg} | | -55 ... +175 | °C |
| IEC climatic category; DIN IEC 68-1 | | | 55/175/56 | |

| Parameter | Symbol | Conditions | Values | | | Unit |
|-----------|--------|------------|--------|------|------|------|
| | | | min. | typ. | max. | |

Thermal characteristics

| | | | | | | |
|--|------------|--|---|---|-----|-----|
| Thermal resistance, junction - case | R_{thJC} | | - | - | 2.2 | K/W |
| Thermal resistance, junction - ambient, leaded | R_{thJA} | | - | - | 100 | |
| SMD version, device on PCB | R_{thJA} | minimal footprint | - | - | 75 | |
| | | 6 cm ² cooling area ²⁾ | - | - | 50 | |

Electrical characteristics, at $T_j=25\text{ }^\circ\text{C}$, unless otherwise specified
Static characteristics

| | | | | | | |
|----------------------------------|---------------|---|-----|------|-----|---------------|
| Drain-source breakdown voltage | $V_{(BR)DSS}$ | $V_{GS}=0\text{ V}, I_D=1\text{ mA}$ | 55 | - | - | V |
| Gate threshold voltage | $V_{GS(th)}$ | $V_{DS}=V_{GS}, I_D=26\text{ }\mu\text{A}$ | 1.2 | 1.6 | 2.0 | |
| Zero gate voltage drain current | I_{DSS} | $V_{DS}=55\text{ V}, V_{GS}=0\text{ V}, T_j=25\text{ }^\circ\text{C}$ | - | 0.01 | 1 | μA |
| | | $V_{DS}=55\text{ V}, V_{GS}=0\text{ V}, T_j=125\text{ }^\circ\text{C}^{1)}$ | - | 1 | 100 | |
| Gate-source leakage current | I_{GSS} | $V_{GS}=20\text{ V}, V_{DS}=0\text{ V}$ | - | 1 | 100 | nA |
| Drain-source on-state resistance | $R_{DS(on)}$ | $V_{GS}=4.5\text{ V}, I_D=13\text{ A}$ | - | 34 | 47 | m Ω |
| Drain-source on-state resistance | $R_{DS(on)}$ | $V_{GS}=10\text{ V}, I_D=13\text{ A}$ | - | 27 | 35 | |

| Parameter | Symbol | Conditions | Values | | | Unit |
|-----------|--------|------------|--------|------|------|------|
| | | | min. | typ. | max. | |

Dynamic characteristics¹⁾

| | | | | | | |
|------------------------------|--------------|--|---|-----|---|----|
| Input capacitance | C_{iss} | $V_{GS}=0\text{ V}, V_{DS}=25\text{ V},$ $f=1\text{ MHz}$ | - | 621 | - | pF |
| Output capacitance | C_{oss} | | - | 178 | - | |
| Reverse transfer capacitance | C_{rss} | | - | 63 | - | |
| Turn-on delay time | $t_{d(on)}$ | $V_{DD}=30\text{ V}, V_{GS}=10\text{ V},$ $I_D=26\text{ A}, R_G=11\ \Omega$ | - | 5 | - | ns |
| Rise time | t_r | | - | 18 | - | |
| Turn-off delay time | $t_{d(off)}$ | | - | 26 | - | |
| Fall time | t_f | | - | 11 | - | |

Gate Charge Characteristics¹⁾

| | | | | | | |
|-----------------------|---------------|--|---|-----|----|----|
| Gate to source charge | Q_{gs} | $V_{DD}=44\text{ V}, I_D=26\text{ A},$ $V_{GS}=0\text{ to }10\text{ V}$ | - | 1 | 3 | nC |
| Gate to drain charge | Q_{gd} | | - | 4 | 9 | |
| Gate charge total | Q_g | | - | 10 | 24 | |
| Gate plateau voltage | $V_{plateau}$ | | - | 4.0 | - | V |

Reverse Diode

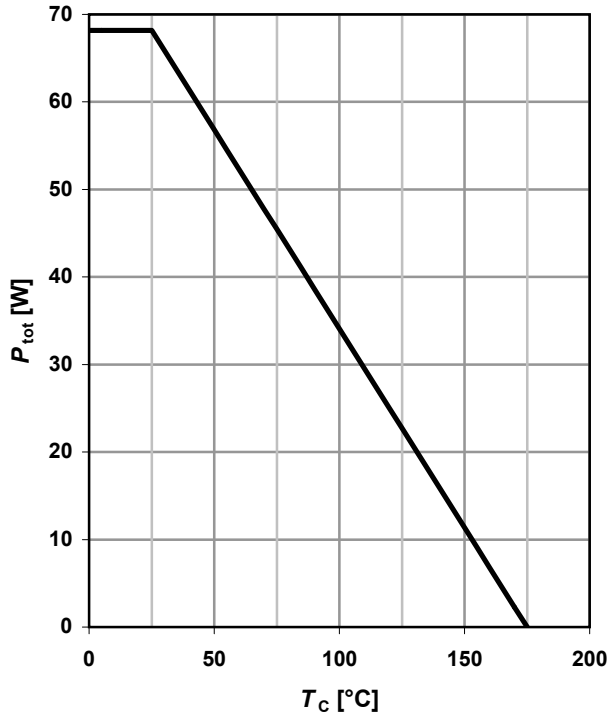
| | | | | | | |
|--|---------------|---|---|------|-----|----|
| Diode continuous forward current ¹⁾ | I_S | $T_C=25\text{ }^\circ\text{C}$ | - | - | 30 | A |
| Diode pulse current ¹⁾ | $I_{S,pulse}$ | | - | - | 120 | |
| Diode forward voltage | V_{SD} | $V_{GS}=0\text{ V}, I_F=26\text{ A},$ $T_J=25\text{ }^\circ\text{C}$ | - | 0.95 | 1.3 | V |
| Reverse recovery time ¹⁾ | t_{rr} | $V_R=30\text{ V}, I_F=I_S,$ $di_F/dt=100\text{ A}/\mu\text{s}$ | - | 40 | - | ns |
| Reverse recovery charge ¹⁾ | Q_{rr} | $V_R=30\text{ V}, I_F=I_S,$ $di_F/dt=100\text{ A}/\mu\text{s}$ | - | 36 | - | nC |

¹⁾ Defined by design. Not subject to production test.

²⁾ Device on 40 mm x 40 mm x 1.5 mm epoxy PCB FR4 with 6 cm² (one layer, 70 μm thick) copper area for drain connection. PCB is vertical in still air.

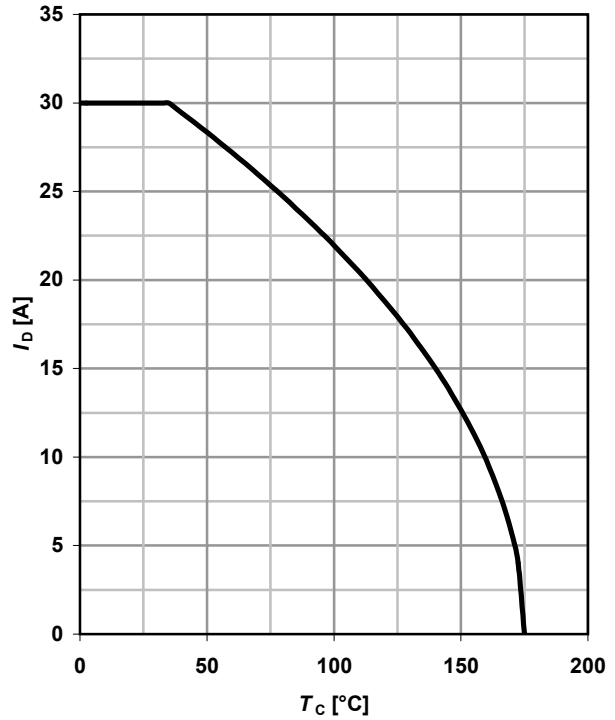
1 Power dissipation

$P_{tot} = f(T_C); V_{GS} \geq 6 V$



2 Drain current

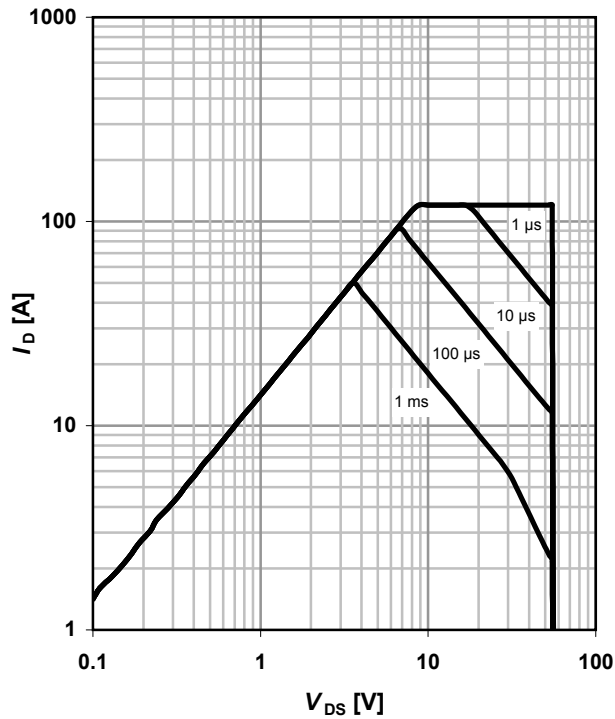
$I_D = f(T_C); V_{GS} \geq 10 V$



3 Safe operating area

$I_D = f(V_{DS}); T_C = 25\text{ °C}; D = 0$

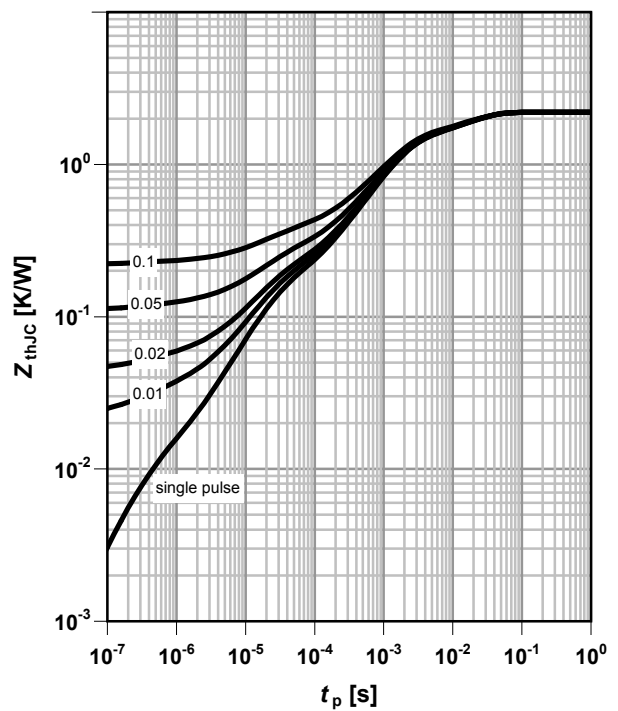
parameter: t_p



4 Max. transient thermal impedance

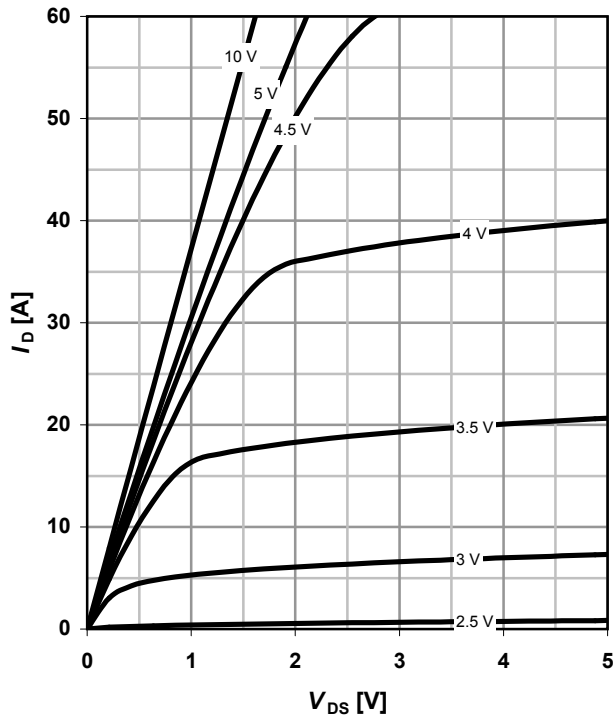
$Z_{thJC} = f(t_p)$

parameter: $D = t_p/T$

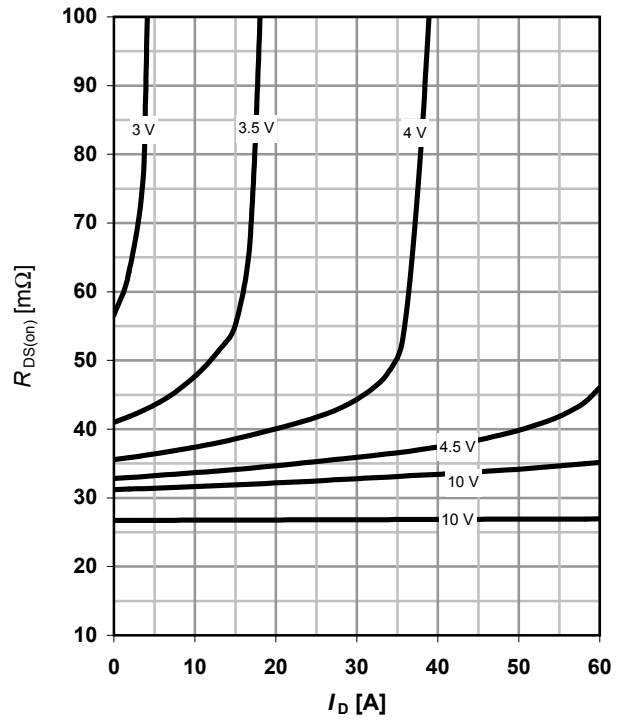


5 Typ. output characteristics

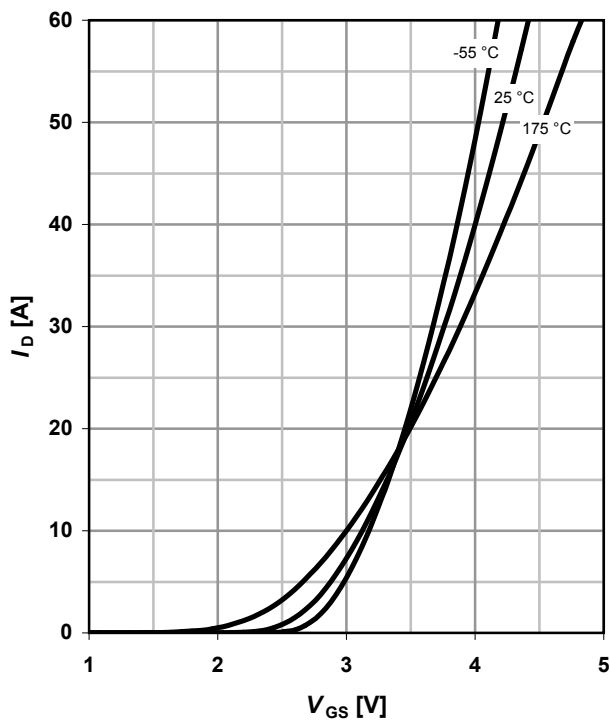
$$I_D = f(V_{DS}); T_j = 25^\circ\text{C}$$

 parameter: V_{GS}

6 Typ. drain-source on-state resistance

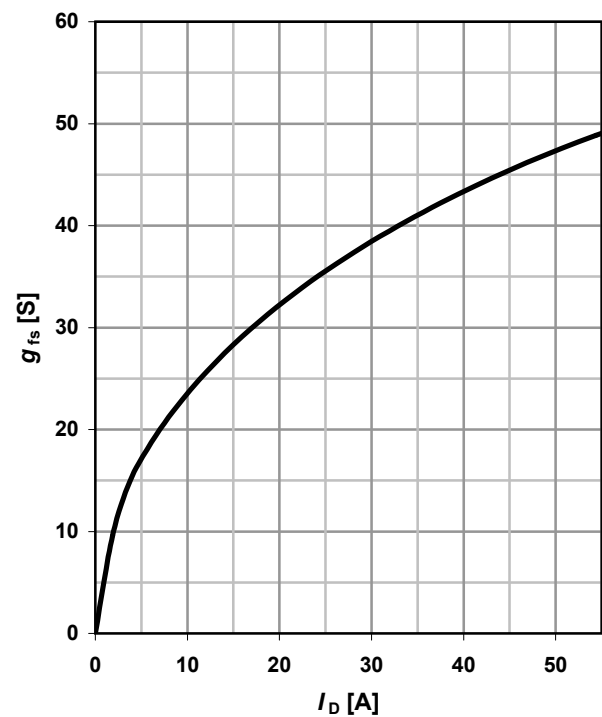
$$R_{DS(on)} = f(I_D); T_j = 25^\circ\text{C}$$

 parameter: V_{GS}

7 Typ. transfer characteristics

$$I_D = f(V_{GS}); V_{DS} = 6\text{V}$$

 parameter: T_j

8 Typ. Forward transconductance

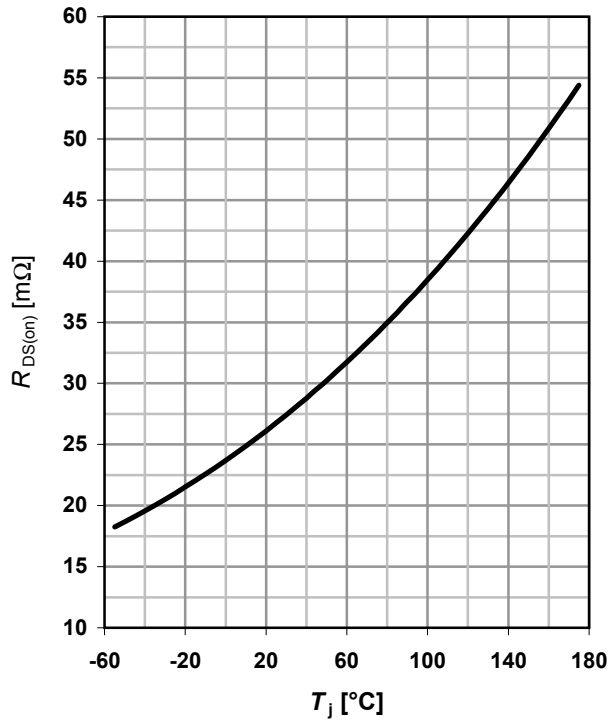
$$g_{fs} = f(I_D); T_j = 25^\circ\text{C}$$

 parameter: g_{fs}


9 Typ. Drain-source on-state resistance

$R_{DS(ON)} = f(T_j)$

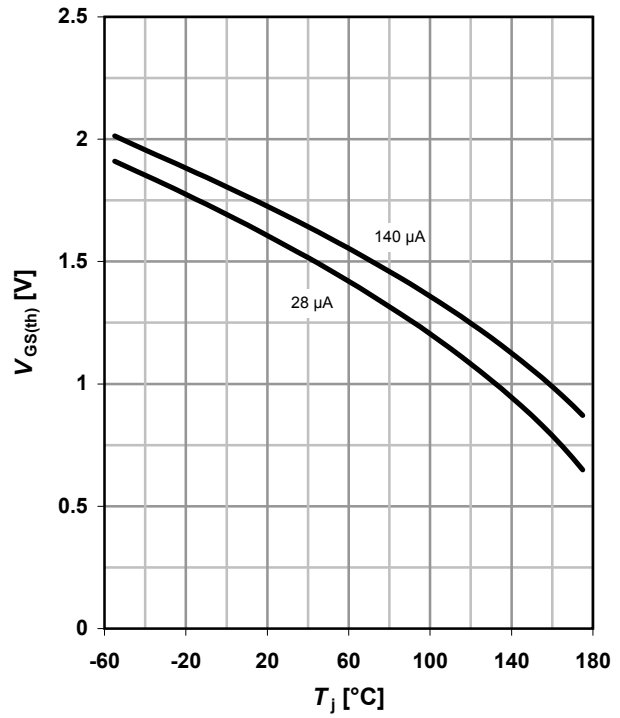
parameter: $I_D = 13\text{ A}$; $V_{GS} = 10\text{ V}$



10 Typ. gate threshold voltage

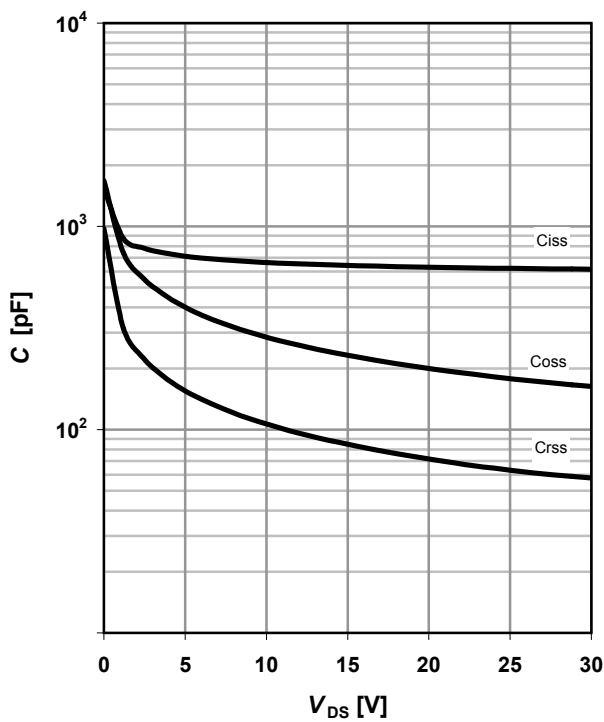
$V_{GS(th)} = f(T_j)$; $V_{GS} = V_{DS}$

parameter: I_D



11 Typ. capacitances

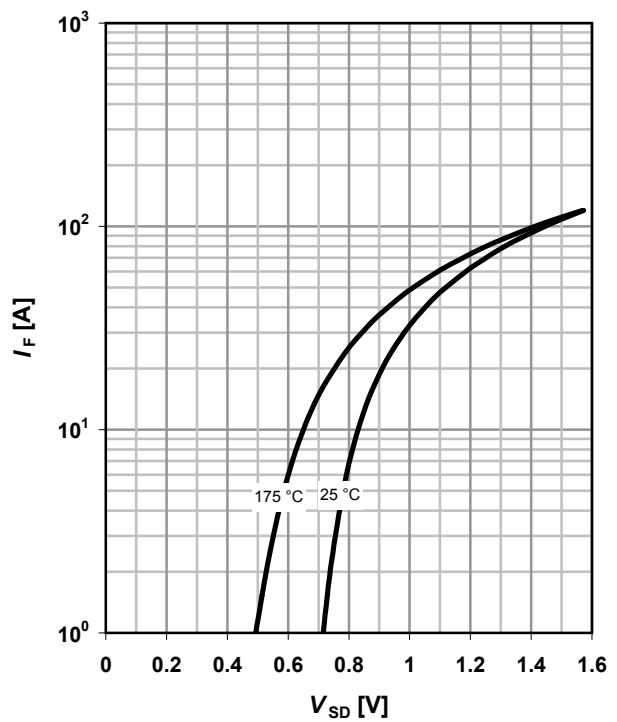
$C = f(V_{DS})$; $V_{GS} = 0\text{ V}$; $f = 1\text{ MHz}$



12 Typical forward diode characteristics

$I_F = f(V_{SD})$

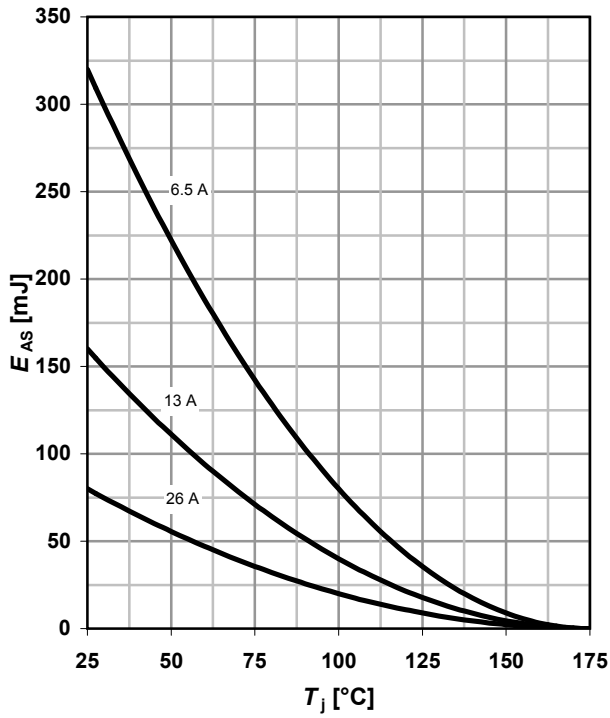
parameter: T_j



13 Typical avalanche energy

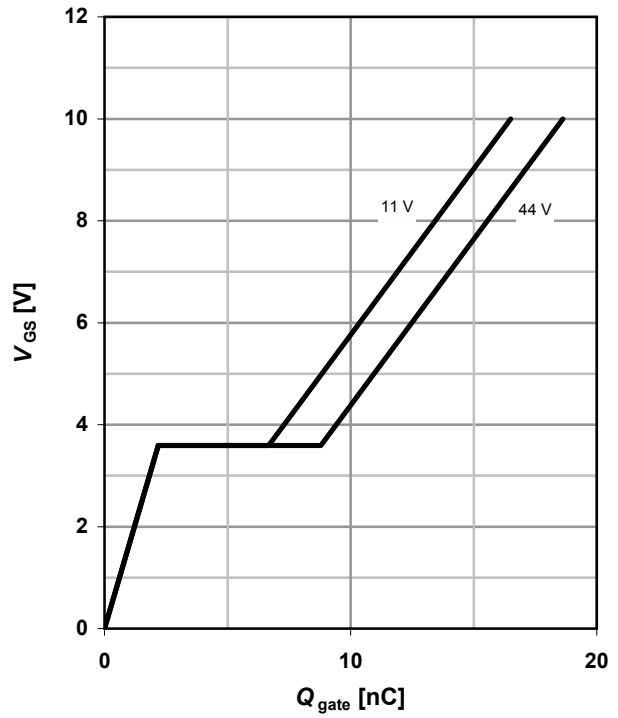
$E_{AS} = f(T_j)$

parameter: I_D



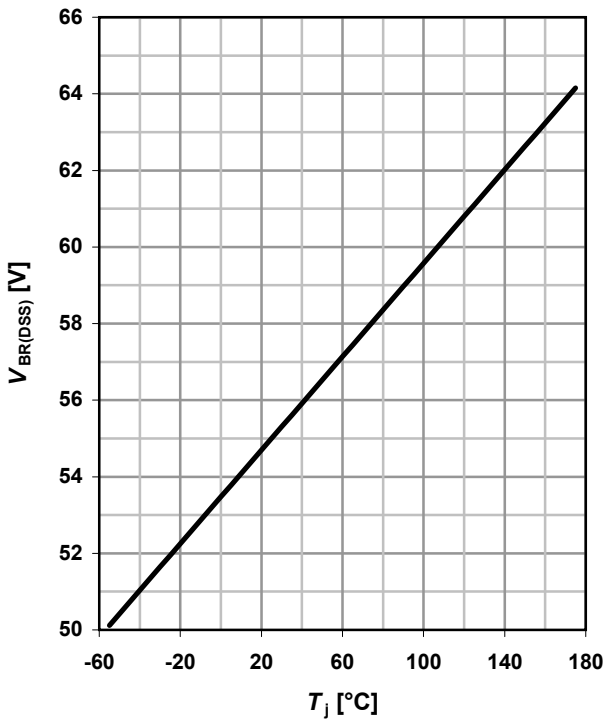
14 Typ. gate charge

$V_{GS} = f(Q_{gate}); I_D = 26 \text{ A pulsed}$

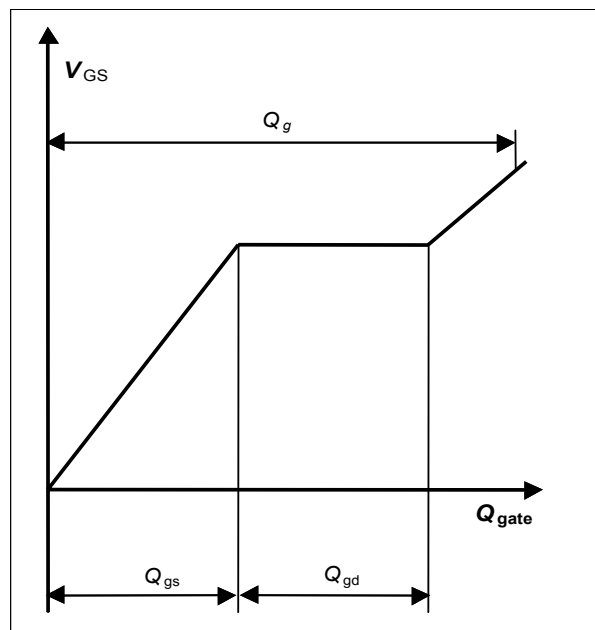


15 Typ. drain-source breakdown voltage

$V_{BR(DSS)} = f(T_j); I_D = 1 \text{ mA}$



16 Gate charge waveforms



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